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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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# **SMT POWER INDUCTORS**

## Shielded Drum Core - P1172NL/P1173NL Series







Height: 8.0mm Max

• Footprint: 12.2mm x 12.2mm Max

Current Rating: up to 14A

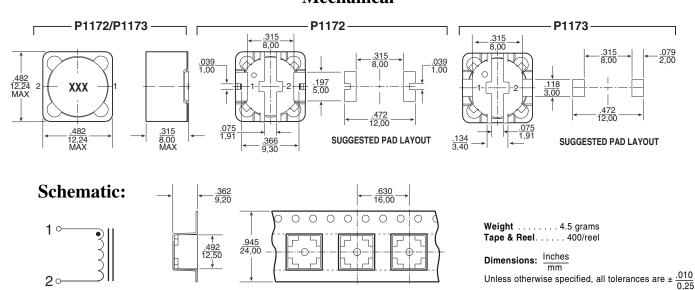
Inductance Range: .8μH to 51μH

Part <sup>2,3</sup> Numbers		Inductance @ 0 A DC (μH)	Inductance @Irated (µH) MIN	Irated <sup>5</sup> (ADC)	DCR (mΩ)		Saturation <sup>6</sup> Current -25% (A)	Heating <sup>7</sup> Current +40°C(A)	Core Loss <sup>8</sup> Factor (K2)	SRF (MHz)
					TYP MAX					
P1172.132NL	P1173.132NL	1.3*	0.8	14	2.3	3	15	14	90	>40
P1172.202NL	P1173.202NL	2.0*	1.3	10	4.5	6	13	10	110	>40
P1172.272NL	P1173.272NL	2.7*	1.8	9	5.8	7.3	11	9	130	>40
P1172.372NL	P1173.372NL	3.7*	2.4	8.3	6.8	8.5	9.2	8.3	150	37
P1172.472NL	P1173.472NL	4.7*	3.1	7.9	7.6	9.5	8.2	7.9	170	33
P1172.602NL	P1173.602NL	6.0*	3.9	6	13	16.5	6.9	6	200	30
P1172.762NL	P1173.762NL	7.6*	4.9	5.7	14.3	18.5	6.2	5.7	220	25
P1172.103NL	P1173.103NL	10	7.5	5.2	17.3	21.8	5.5	5.2	250	20
P1172.123NL	P1173.123NL	12	9	4.5	23.3	29	5.1	4.5	280	18
P1172.153NL	P1173.153NL	15	11.3	4.1	28.3	35.4	4.4	4.1	300	15
P1172.183NL	P1173.183NL	18	13.5	4	29.4	37	4.3	4	340	13
P1172.223NL	P1173.223NL	22	16.5	3.8	33.2	42	3.8	3.8	370	12
P1172.273NL	P1173.273NL	27	20.3	3.4	36.2	45.9	3.4	3.6	410	11
P1172.333NL	P1173.333NL	33	24.8	3	49.3	64.8	3	3.1	460	10
P1172.393NL	P1173.393NL	39	29.3	2.7	65.2	81.5	2.8	2.7	490	8
P1172.473NL	P1173.473NL	47	35.3	2.6	71.4	89	2.6	2.6	550	7
P1172.683NL	P1173.683NL	68	51	2.1	108	135	2.1	2.1	670	6

<sup>\*</sup>Inductance at OApc tolerance on indicated part numbers is ±30%; tolerance is ±20% on all other parts.

NOTES FROM TABLE: (See page 43)

#### Mechanical



**TAPE & REEL LAYOUT** 

### **SMT POWER INDUCTORS**

### **Shielded Drum Core Series**



**Notes from Tables** (pages 27 - 42)

- 1. Unless otherwise specified, all testing is made at 100kHz, 0.1VAC.
- Optional Tape & Reel packaging can be ordered by adding a "T" suffix to the part number (i.e. P1166.102NL becomes P1166.102NLT). Pulse complies with industry standard Tape and Tape & Reel specification EIA481.
- 3. The "NL" suffix indicates an RoHS-compliant part number. Non-NL suffixed parts are not necessarily RoHS compliant, but are electrically and mechanically equivalent to NL versions. If a part number does not have the "NL" suffix, but an RoHS compliant version is required, please contact Pulse for availability.
- 4. Temperature of the component (ambient plus temperature rise) must be within specified operating temperature range.
- 5. The rated current (Irated) as listed is either the saturation current or the heating current depending on which value is lower.
- 6. The saturation current, Isat, is the current at which the component inductance drops by the indicated percentage (typical) at an ambient temperature of 25°C. This current is determined by placing the component in the specified ambient environment and applying a short duration pulse current (to eliminate self-heating effects) to the component.
- 7. The heating current, Idc, is the DC current required to raise the component temperature by the indicated delta (approximately). The heating current is determined by mounting the component on a typical PCB and applying current for 30 minutes. The temperature is measured by placing the thermocouple on top of the unit under test.

8.	In high volt*time (Et) or ripple current applications, addi-
	tional heating in the component can occur due to core
	losses in the inductor which may necessitate derating
	the current in order to limit the temperature rise of the
	component. In order to determine the approximate total
	loss (or temperature rise) for a given application, both
	copper losses and core losses should be taken into
	account.

#### **Estimated Temperature Rise:**

**Trise** =  $[Total loss (mW) / K0]^{.833} (°C)$ 

**Total loss** = Copper loss + Core loss (mW)

Copper loss = IRMS<sup>2</sup> x DCR (Typical) (mW)

Irms =  $[IDC^2 + \Delta I^2/12]^{1/2}$  (A)

**Core loss** = K1 x f (kHz) $^{1.23}$  x Bac(Ga) $^{2.38}$  (mW)

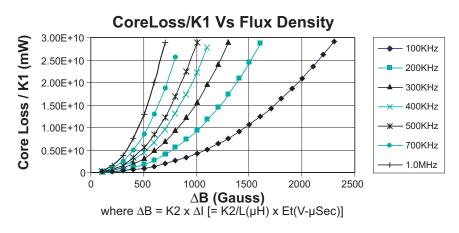
Bac (peak to peak flux density) =  $K2 \times \Delta I$  (Ga)

 $[= K2/L(\mu H) \times Et(V-\mu Sec) (Ga)]$ 

where f varies between 25kHz and 1MHz, and Bac is less than 2500 Gauss.

K2 is a core size and winding dependant value and is given for each p/n in the proceeding datasheets. K0 & K1 are platform and material dependant constants and are given in the table below for each platform.

Part No.	Trise Factor (K0)	Core Loss Factor (K1)
PG0085/86	2.3	5.29E-10
PG0087	5.8	15.2E-10
PG0040/41	0.8	2.80E-10
P1174	0.8	6.47E-10
PF0601	4.6	14.0E-10
PF0464	3.6	24.7E-10
PF0465	3.6	33.4E-10
P1166	1.9	29.6E-10
P1167	2.1	42.2E-10
PF0560NL	5.5	136E-10
P1168/69	4.8	184E-10
P1170/71	4.3	201E-10
P1172/73	5.6	411E-10
PF0552NL	8.3	201E-10
PF0553NL	7.1	411E-10



Take note that the component's temperature rise varies depending on the system condition. It is suggested that the component be tested at the system level, to verify the temperature rise of the component during system operation.